

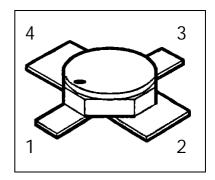
HiRel NPN Silicon RF Transistor

- HiRel Discrete and Microwave Semiconductor
- For low noise, high-gain amplifiers up to 2GHz.
- For linear broadband amplifiers
- Hermetically sealed microwave package
- f_T= 8 GHz F = 2.3 dB at 2 GHz



ESA/SCC Detail Spec. No.: 5611/006

Type Variant No. 06



ESD: Electrostatic discharge sensitive device, observe handling precautions!

Туре	Marking	Ordering Code	Pin Configuration			Package	
			1	2	3 4		
BFY193 (ql)	-	see below	С	Е	В	Е	Micro-X1

(ql) Quality Level: P: Professional Quality, Ordering Code: Q62702F1610

H: High Rel Quality,S: Space Quality,ES: ESA Space Quality,Ordering Code: on requestOrdering Code: Q62702F1701

(see order instructions for ordering example)



Maximum Ratings

Parameter	Symbol	Values	Unit
Collector-emitter voltage	V_{CEO}	12	V
Collector-emitter voltage, V _{BE} =0	V_{CES}	20	V
Collector-base voltage	V_{CBO}	20	V
Emitter-base voltage	V_{EBO}	2	V
Collector current	I _C	80	mA
Base current	I _B	10 ¹⁾	mA
Total power dissipation, $T_S \le 104^{\circ}C^{-2), 3)}$	P _{tot}	580	mW
Junction temperature	T _j	200	°C
Operating temperature range	T _{op}	-65+200	°C
Storage temperature range	T _{stg}	-65+200	°C
Thermal Resistance	<u>.</u>		
Junction-soldering point 3)	R _{th JS}	< 165	K/W

Notes.:

Electrical Characteristics

at $T_A=25$ °C; unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-base cutoff current	I _{CBO}	-	-	100	μΑ
$V_{CB} = 20 \text{ V}, I_{E} = 0$					
Collector-emitter cutoff current	I _{CEX}	-	-	600	μΑ
$V_{CE} = 12 \text{ V}, I_{B} = 0.5 \mu A^{-1.}$					
Collector-base cutoff current	I _{CBO}	-	-	50	nA
$V_{CB} = 10 \text{ V}, I_{E} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	25	μΑ
$V_{EB} = 2 \text{ V}, I_{C} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	0.5	μΑ
$V_{EB} = 1 \text{ V}, I_{C} = 0$					

Notes:

1.) This Test assures V(BR)CE0 > 12V

¹⁾ The maximum permissible base current for V_{FBE} measurements is 30mA (spotmeasurement duration < 1s)

²⁾ At $T_S = +\ 104\ ^{\circ}\text{C}$. For $T_S > +\ 104\ ^{\circ}\text{C}$ derating is required. 3) T_S is measured on the collector lead at the soldering point to the pcb.



Electrical Characteristics (continued)

Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
DC Characteristics	•	•	•	•	
Base-Emitter forward voltage	V_{FBE}	-	-	1	V
$I_E = 30 \text{ mA}, I_C = 0$					
DC current gain	h _{FE}	50	100	175	-
$I_C = 30 \text{ mA}, V_{CE} = 8 \text{ V}$					
AC Characteristics					
Transition frequency	f _T				GHz
I_C = 40mA, V_{CE} = 5 V, f = 500 MHz		6,5	7.5	-	
$I_C = 50 \text{ mA}, V_{CE} = 8 \text{ V}, f = 500 \text{ MHz}$		-	8	-	
Collector-base capacitance	ССВ	-	0.56	0.75	pF
$V_{CB} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Collector-emitter capacitance	C_{CE}	-	0.34	-	pF
V_{CE} = 10 V, V_{BE} = vbe = 0, f = 1 MHz					
Emitter-base capacitance	C _{EB}	-	1.9	2.4	pF
$V_{EB} = 0.5V$, $V_{CB} = vcb = 0$, $f = 1 MHz$					
Noise Figure	F	-	2.3	2.9	dB
$I_{C} = 15 \text{ mA}, V_{CE} = 5 \text{ V}, f = 2 \text{ GHz},$					
$Z_S = Z_{Sopt}$					
Power gain	Gma 1.)	12.5	13.5	-	dB
I_C = 40 mA, V_{CE} = 5V, f = 2 GHz					
$Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$					
Transducer gain	$\left S_{21e}\right ^2$	8	9	-	dB
$I_C = 40 \text{ mA}$, $V_{CE} = 5 \text{ V}$, $f = 2 \text{ GHz}$					
$Z_S = Z_L = 50 \Omega$					
Output Power	P _{OUT}	16.5	17.5	-	dBm
I_C = 50 mA, V_{CE} = 5 V, f = 2GHz,					
P_{IN} =10dBm, $Z_S = Z_L = 50 \Omega$					

Notes.:
1.)
$$G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$



Order Instructions:

Full type variant including quality level must be specified by the orderer. For *HiRel* Discrete and Microwave Semiconductors the ordering code specifies device family and quality level.

Ordering Form:

Ordering Code: Q.....

BFY193 (ql)

(ql): Quality Level

Ordering Example:

Ordering Code: Q62702F1701

BFY193 ES

For BFY193 in ESA Space Quality Level

Further Informations:

See our WWW-Pages:

Discrete and RF-Semiconductors (Small Signal Semiconductors)
 www.infineon.com/product/discrete/hirel.htm

 HiRel Discrete and Microwave Semiconductors www.infineon.com/product/discrete/hirel.htm

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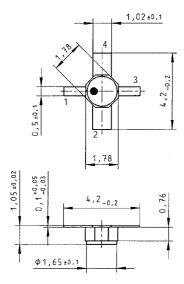
Address: Infineon Technologies Semiconductors,

High Frequency Products Marketing,

P.O.Box 801709, D-81617 Munich



Micro-X1 Package



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